

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1067is#pbf

(Engineering Calculation)

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TOTAL MASS (g) : 0.157213

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004216 | 1000000 | 26817.171875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.051070 | 975000 | 324846.53125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001257 | 24000 | 7995.53759766 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000016 | 300 | 101.772941589 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000037 | 700 | 235.349945068 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.052380 | 1000000 | 333179.1875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.002954 | 1000000 | 18787.9472656 | | |
| | | External Plating Total: | | | | 0.002954 | 1000000 | 18787.9472656 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000419 | 1000000 | 2665.17895508 | | |
| Internal Plating Total: | | | | 0.000419 | 1000000 | 2665.17895508 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001155 | 750000 | 7346.73388672 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000385 | 250000 | 2448.91162109 | | |
| Die Attach Total: | | | | 0.001540 | 1000000 | 9795.64648438 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.012389 | 130000 | 78804.0625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.079099 | 830000 | 503133.65625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.003336 | 35000 | 21219.6601562 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000477 | 5000 | 3034.10595703 | | |
| | | Encapsulation Total: | | | | 0.095301 | 1000000 | 606191.4375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000403 | 1000000 | 2563.40625 | | |
| | | | | | TOTAL MASS (g) : | 0.157213 | | |